

Silicon P Channel MOS FET High Speed Power Switching



ADE-208-519 1st. Edition

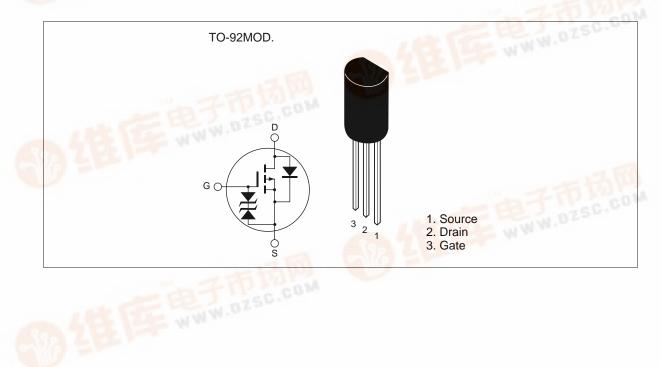
WWW.0ZSC.CI

Features

- Low on-resistance
 - $R_{DS(on)} = 0.08\Omega$ typ (at $V_{GS} = -10$ V, $I_D = -2.5$ A)
- 4V gate drive devices.
- WWW.0250.00W Large current capacitance •

Outline

 $I_D = -5 A$





Absolute Maximum Ratings (Ta = 25° C)

Symbol	Ratings	Unit	
V _{DSS}	-30	V	
V _{GSS}	±20	V	
I _D	-5	А	
Note1 D(pulse)	-20	А	
I _{DR}	-5	А	
Pch	0.9	W	
Tch	150	٥C	
Tstg	-55 to +150	٥C	
	V _{DSS} V _{GSS} I _D I _{D(pulse)} ^{Note1} I _{DR} Pch Tch	V_{DSS} -30 V_{GSS} ± 20 I_D -5 $I_{D(pulse)}^{Note1}$ -20 I_{DR} -5 Pch 0.9 Tch 150	V _{DSS} -30 V V _{GSS} ± 20 V I _D -5 A I _{D(pulse)} ^{Note1} -20 A I _{DR} -5 A ICR -5 A IDR 0.9 W Tch 150 °C

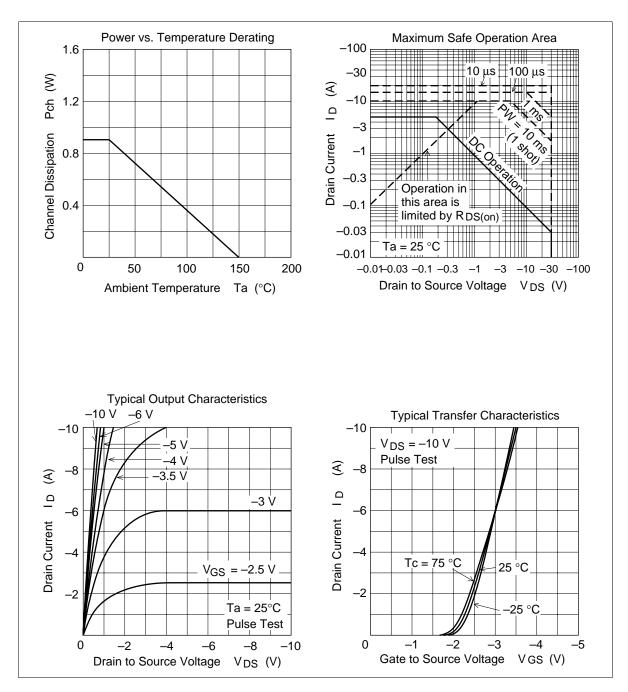
Note: 1. $PW \le 10\mu s$, duty cycle $\le 1 \%$

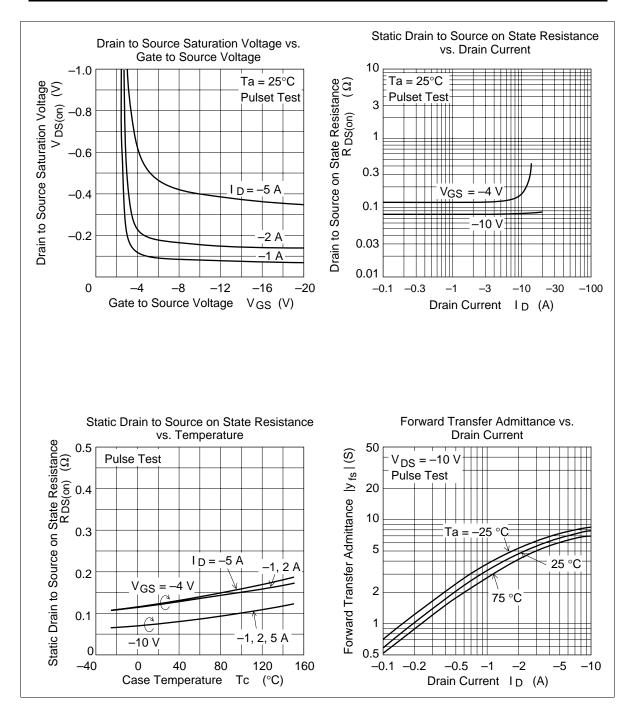
Electrical Characteristics (Ta = 25°C)

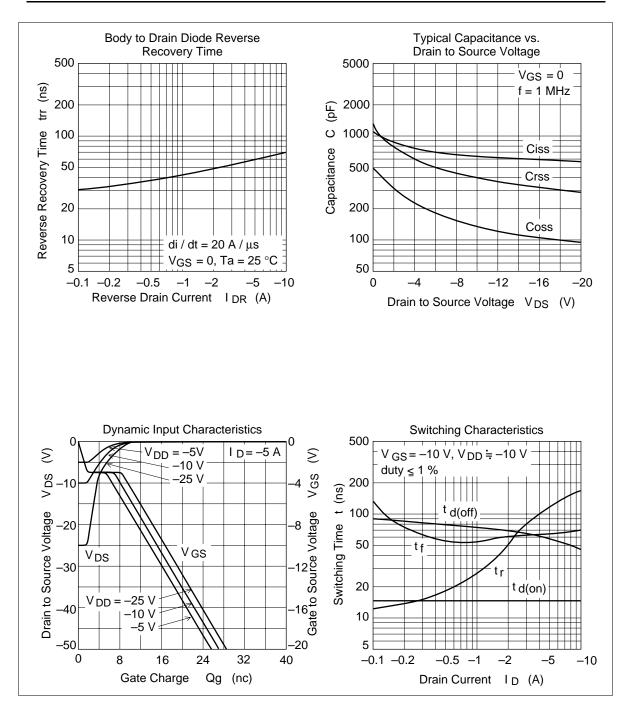
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{\rm (BR)DSS}$	-30	_	_	V	$I_{\rm D} = -10 {\rm mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{\rm (BR)GSS}$	±20	—	_	V	$I_{g} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	—	—	-10	μΑ	$V_{\rm DS} = -30$ V, $V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}	—	—	±10	μA	$V_{\text{GS}}=\pm 16V, \ V_{\text{DS}}=0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$I_{\rm D} = -1$ mA, $V_{\rm DS} = -10$ V
Static drain to source on state resistance	$R_{DS(on)}$	—	0.08	0.11	Ω	$I_{\rm D} = -2.5 {\rm A}$ $V_{\rm GS} = -10 {\rm V}^{*1}$
	R _{DS(on)}	—	0.12	0.17	Ω	$I_{\rm D} = -2.5 {\rm A}$ $V_{\rm GS} = -4 {\rm V}^{*1}$
Forward transfer admittance	y _{fs}	3	5	—	S	$I_{\rm D} = -2.5 {\rm A},$ $V_{\rm DS} = -10 {\rm V}^{*1}$
Input capacitance	Ciss	—	630	—	pF	$V_{\rm DS} = -10V$
Output capacitance	Coss	—	390	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	135	—	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	—	15	—	ns	$V_{GS} = -10V, I_{D} = -2.5A$
Rise time	t,	—	70	—	ns	$R_{L} = 4\Omega$
Turn-off delay time	t _{d(off)}	_	65	_	ns	
Fall time	t _f	_	60	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-1.0	_	V	$I_{\rm D} = -5A, V_{\rm GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	60	—	ns	$I_F = -5A$, $V_{GS} = 0$ diF/ dt = 20A/µs

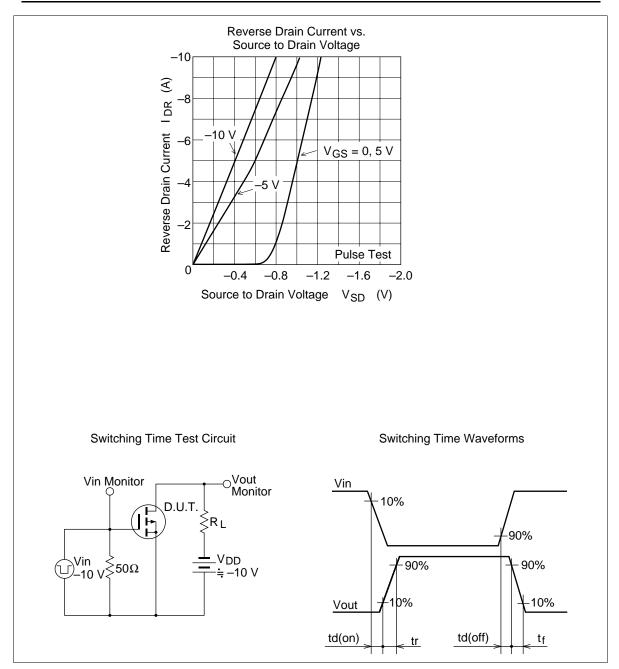
Note: 1. Pulse test

Main Characteristics

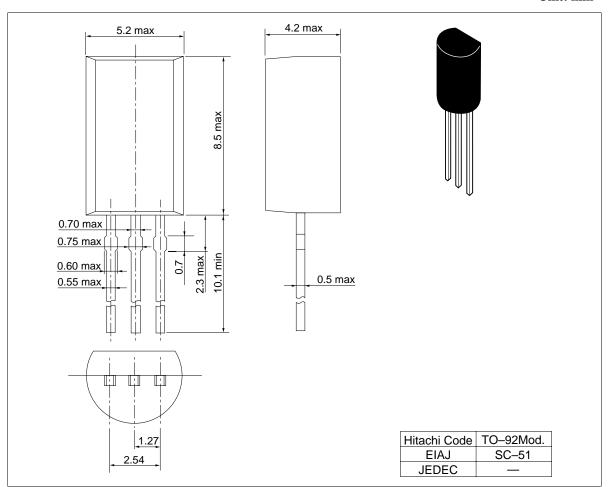








Package Dimensions



Unit: mm

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